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K350QVG-V2-F

(ATP350G01)

Product

Standard LCD Module 320 x RGB x 240 Dots 3.5" 262K colors TFT display Wide temperature With white LED backlight With Touch Panel

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1. Document revision history :							
DOCUMENT REVISION	DATE	DESCRIPTION	PREPARED BY	APPROVED BY			
01 02 03	2008.04.28 2010.06.30 2010.07.15	First Release. Revised typing error Update packing reference	MF Zou MF Zou MF Zou				



2. General Description

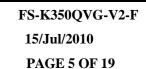
- 3.5"(diagonal), 320 x RGB x 240 dots, 262K colors, Transmissive, TFT LCD module.
- Viewing Direction: 12 o'clock.
- Driving IC: SSD2119 or equivalent TFT controller/driver.
- 18-bits data bus (parallel RGB interface/8080 parallel system interface).
- With Touch Panel.
- With internal voltage booster.
- Logic voltage: 3.3V (typ.).

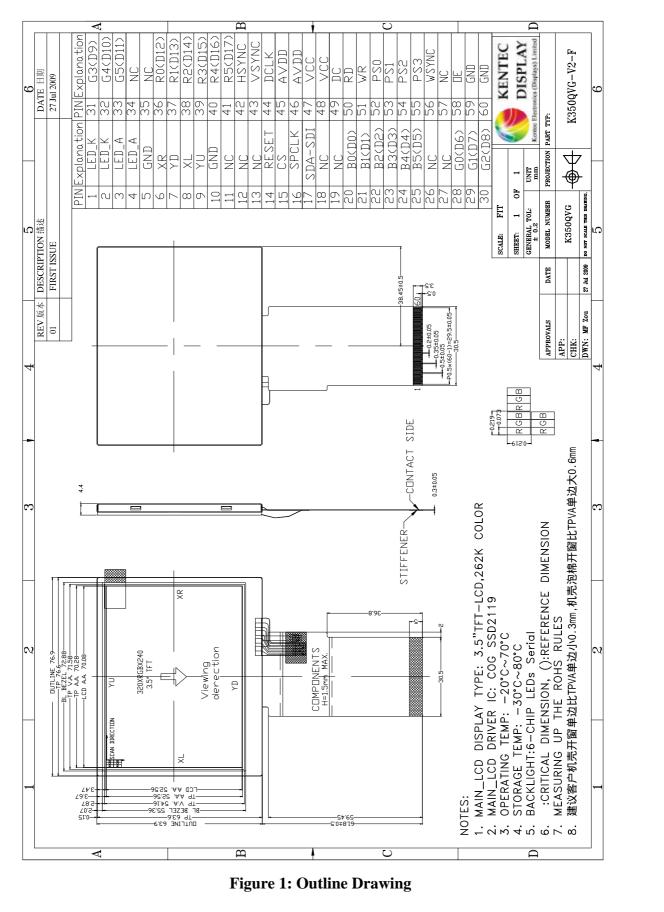
3. Mechanical Specifications

The mechanical detail is shown in Fig. 1 and summarized in Table 1 below.

		Table 1	
Par	rameter	Specifications	Unit
Outline	dimensions	76.9(W) x 63.9(H) x 4.4(D) (Exclude FPC, cables of backlight)	mm
	View area	72.88(W) x 55.36(H)	mm
	TP view area	71.58 (W) x 54.2(H)	mm
Color TFT	LCD active area	70.08(W) x 52.56(H)	mm
320xRGBx240	Display format	320 x RGB x 240	dots
	Color configuration	RGB stripes	-
	Dot size	0.219(RGB)(W) x 0.219(H)	mm
V	Veight	~40	grams









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4. Interface signals

	errace signal	Table 2: Pin assignment						
Pin No.	Symbol	Description						
1-2	LED_K							
3-4	LED_A	– Power supply for LED backlight						
5	GND	Power supply (system ground)						
6	XR							
7	YD							
8	XL	- Terminal of touch panel.						
9	YU	-						
10	GND	Power supply (system ground)						
11-13	NC	No connection						
14	RESET	System reset pin						
15	CS	Chip select pin						
16	SPCLK	Clock pin of serial interface						
10	SDA-SDI	Data pin of serial interface						
18-19	NC	No connection						
20-25	B[0-5]	Blue data 6-bit/18bit bi-directional (D0-D5)						
26-27	NC	No connection						
28-33	G[0-5]	Green data 6-bit/18bit bi-directional (D6-D11)						
34-35	NC	No connection						
36-41	R[0-5]	Red data 6-bit/18bit bi-directional (D12-D17)						
42	HSYNC	Line synchronization signal input						
43	VSYNC	Frame /Ram synchronization signal input						
44	DCLK	Dot clock signal						
45-46	AVDD	Supply voltage for lcd driving						
47-48	VCC	Supply voltage for logic						
49	DC	Parallel Interface						
50	RD	I80 system: Serves as a read signal and reads data at the low level.						
51	WR	I80 system: Serves as a write signal and writes data at the rising edge.						
		Interface selection pin						
1		PS3PS2PS1PS0Interface mode						
1		0 0 1 0 16-bit 8080 parallel interface, D[17:10]&D[8:1]						
1		0 0 1 1 8-bit 8080 parallel interface, D[8:1]						
1		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$						
52-55	PS[0:3]	0 1 0 1 16-bit RGB(262K colour) + 3-wire SPI,						
52 55	10[0.5]	D[17:10]&D[8:1]						
1		0 1 1 0 18-bit RGB(262K colour) + 3-wire SPI, D[17:0]						
1		0 1 1 1 6-bit RGB(262K colour) + 3-wire SPI, D[8:3]						
1		1 0 1 0 18-bit 8080 parallel interface, D[17:0]						
1		1 0 1 1 9-bit 8080 parallel interface, D[8:0]						
		1 1 1 0 3-wire SPI						
56	WSYNC	Ram Write Synchronization output						
57	NC	No connection						
58 59-60	OE GND	Display enable pin from controller						
		Power supply (system ground)						



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5. Absolute Maximum Ratings

5.1 Electrical Maximum Ratings – for IC Only

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Table 3:	Electrical	Maximum	Ratings -	- for IC
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Parameter	Symbol	Min.	Max.	Unit	Note
Supply voltage	VCC	-0.3	+4.0	V	1
Input voltage	AVDD	-0.3	+5.0	V	

Note:

1.VCC, GND must be maintained.

2. The modules may be destroyed if they are used beyond the absolute maximum ratings.

5.2 Environmental Condition

		Table 4			
Item	Operating temperature (Topr)		Storage temperature (Tstg) (Note 1)		Remark
	Min.	Max.	Min.	Max.	
Ambient temperature	-20°C	+70°C	-30°C	+80°C	Dry
Humidity (Note 1)	80 < 50% RH for 40°	No condensation			

Note 1: Product cannot sustain at extreme storage conditions for long time.

6. Electrical Specifications

Typical Electrical Characteristics

At Ta = 25 °C, VCC=IOVCC= 3.3V, GND=0V.

		Table 5				
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage (logic)	VCC-GND		1.4	-	3.6	V
Supply voltage (lcd driving)	AVDD		2.5 or VDDIO	-	3.6	V
	VGH		9	-	18.0	V
Output voltage(LCD)	VGL		-15.0	-	-6	V
	VCOM		-1	-	6	V
Supply current (Logic & LCD)	ICC	VDD=3.3V	-	-	10	mA
Supply voltage of white LED backlight	VLED	Forward current =20 mA	-	19.2	21.6	V
Luminance (on the module surface)		Number of LED dies = 6	230	270	-	cd/m ²



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7. Optical Characteristics

		Table	7: Optical sp	ecifica	<u>tions</u>			
Itoms		Symbol	Condition	Specifications			Unit	
Items		Symbol	Condition	Min.	Тур.	Max.	Om	
Contrast Ra	atio	CR		150	300	-	-	
Response T	imo	T _R		-	15	30	ms	
Response 1	inte	T _F		-	35	50	ms	
	Red	X _R		0.604	0.624	0.644	-	
	Keu	Y _R		0.302	0.322	0.342	-	
	Green	X _G		0.268	0.288	0.308	-	
Chromaticity		Y _G		0.540	0.560	0.580	-	Note
Chromaticity	Blue	X _B		0.127	0.147	0.167	-	INOLE
		Y _B		0.097	0.117	0.137	-	
	White	X_{W}		-	0.307	-	-	
		Y_W		-	0.328	-	-	
	Hor.	<pre>\$\$\\$</pre>		-	45	-		
Viewing angle		\$\$\\$	Center	-	45	-	dag	
Viewing angle	Ver.	$\theta 2(12 \text{ o'clock})$	CR=10	-	15	-	deg.	
	v CI.	$\theta 1(6 \text{ o'clock})$		-	35	-		
NTSC ratio					61.5		%	

Note 1: Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

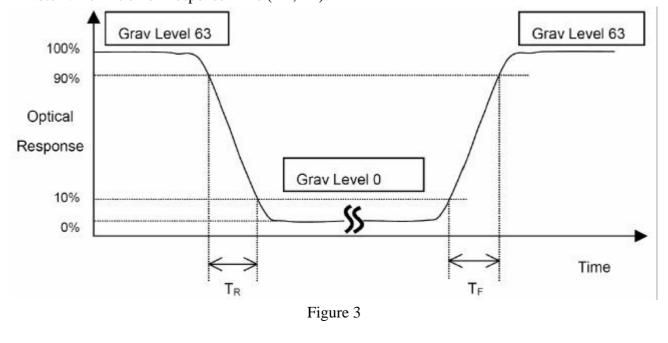
Contrast Ratio (CR) = L63 / L0

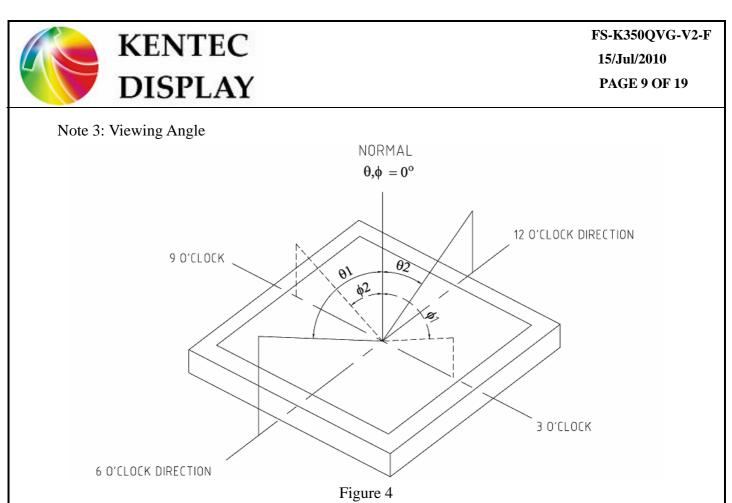
L63: Luminance of gray level 63

L0: Luminance of gray level 0

CR = CR (10)

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note 5. Note 2: Definition of Response Time (TR, TF):

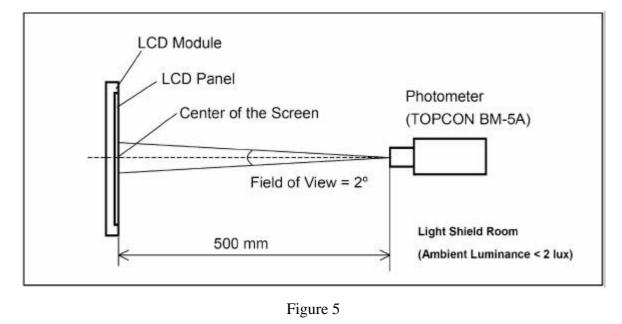




The above "Viewing Angle" is the measuring position with Largest Contrast Ratio; not for good image quality. View Direction for good image quality is 6 O'clock. Module maker can increase the "Viewing Angle" by applying Wide View Film.

Note 4: Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.





8. AC Characteristics

Please refer SSD2119 datasheet.

9. Reliability Test Item

Test Item	Sample Type	Test Condition	Test result determinant gist
High temperature	Normal temperature	70±3 ;96H	the inspection of
storage	Wide temperature	80±3 ;96H	appearance and function
Low temperature	Normal temperature	-20±3 ;120H	character.
storage	Wide temperature	-30±3 ;120H	
High temperature	Normal temperature	50 ±3 ,90%±3%RH;96H	
/humidity storage	Wide temperature	60 ±3 ,90%±3%RH;96H	
High temperature	Normal temperature	60±3 ;96H	no objection of the function
operation	Wide temperature	70±3 ;96H	character; no fatal objection of
Low temperature	Normal temperature	0±3 ;96H	the appearance.
operation	Wide temperature	-20±3 ;96H	
High temperature	Normal temperature	40 ±3 ,90%±3%RH;96H	
/humidity operation	Wide temperature	50 ±3 ,90%±3%RH;96H	
Temperature Shock	Normal temperature	-20±3 ,30min? 70±3 ,30	inspect the objections
		min;10cycle	appearance, function & the
			whole structure
	Wide temperature	-30±3 ,30min	The inspection of appearance,
		80±3,30min;10cycle	function & the whole structure

10. Suggestions for using LCD modules

10.1 Handling of LCM

- 1. The LCD screen is made of glass. Don't give excessive external shock, or drop from a high place.
- 2. If the LCD screen is damaged and the liquid crystal leaks out, do not lick and swallow. When the liquid is attach to your hand, skin, cloth etc, wash it off by using soap and water thoroughly and immediately.
- 3. Don't apply excessive force on the surface of the LCM.
- 4. If the surface is contaminated ,clean it with soft cloth. If the LCM is severely contaminated , use Isopropyl alcohol/Ethyl alcohol to clean. Other solvents may damage the polarizer . The following solvents is especially prohibited: water , ketone Aromatic solvents etc.
- 5. Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by



water droplets, moisture condensation or a current flow in a high-humidity environment.

6. Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.

7. Don't disassemble the LCM.

8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions.
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- 9. Do not alter, modify or change the the shape of the tab on the metal frame.
- 10. Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- 11. Do not damage or modify the pattern writing on the printed circuit board.
- 12. Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector
- 13. Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- 14. Do not drop, bend or twist LCM.

10.2 Cautions for installing and assemabling if the module has Touch Panel

1. Use a buffer material (Gasket) between the touch panel and Front-case to protect damage and wrong operating. The dimension of the buffer material's edge between the TP V.A. edge is Min. 0.3mm.

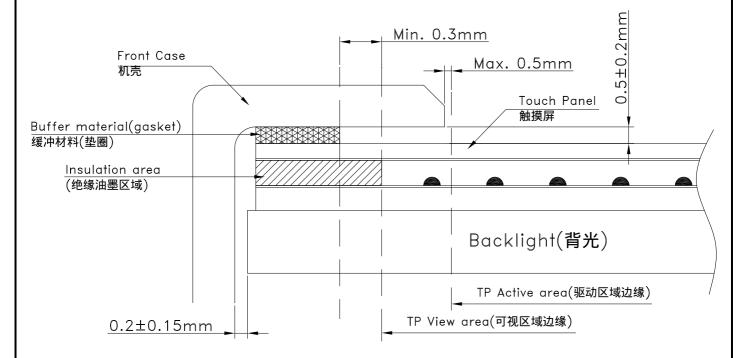
2. We recommend to design a case that it can't over the boundary of the active area Max. 0.5mm in order to prevent an operation at outside of the active area which can't guarantee the specified durability,



because operation at the outside of the active area cause serious damage of a transparent.

3. When design case for installing Module, you would consider give a distance about 0.2 ± 0.15 mm between the module edge to case inside.

4. The corners of the product are not chamfered. When positioning and fixing the product on the case, we sugguest that you would provide a R part on the conner of the case so as not to apply load on the corner of the transparent module.



10.3 Storage

1. Store in an ambient temperature of 5 to 45 °C, and in a relative humidity of 40% to 60%. Don't expose

to sunlight or fluorescent light.

- 2. Storage in a clean environment, free from dust, active gas, and solvent.
- 3. Store in antistatic container.



11. Inspection Standard

This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM with touch pannel.

11.1 Sample plan and Inspection condition

11.1.1 Sample plan

Sampling plan according to MIL-STD-105E, normal level 2 and based on:

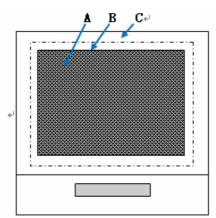
Major defect: AQL 0.65;

Minor defect: AQL 1.5.

11.1.2 Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45 against perpendicular line.

11.2 Definition of inspection zone in LCD



Inspection zones in an LCD

Zone A: character/Digit area;

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area);

Zone C: Outside viewing area (invisible area after assembly in customer's product);

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product. Defects are classified as major defects and minor defects according to the degree of defectiveness defined herein.

11.3 Major defects and Minor defects

11.3.1 Major defects

A major defect is a defect that is likely to result in failure, or to reduce the usability of the product for its intended purpose.

11.3.1.1 Abnormal operation: modules cannot display normally;



11.3.1.2 Line defect;

11.3.1.3 There is serious distortion or sharp burr on mechanical housing;

11.3.1.4 Glass breakage.

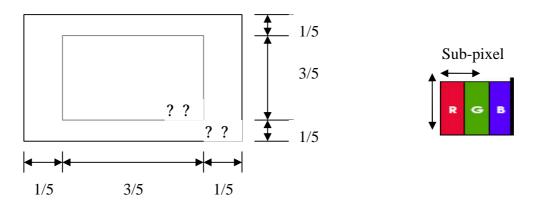
11.3.2 Minor defects:

A minor defect is a defect that is not likely to reduce the usability of the product for its intended purpose.

11.3.2.1 Dot defect:

11.3.2.1.1 Inspection pattern : Full white, full black, red, green and blue screens;

11.3.2.1.2 Criteria :(acceptable);



Note: 1. Dot defect is defined as the defective area of the dot area is larger than 50% of the dot area . And the bright dot defect must be visible through 5% ND filter.

2. Except for the allowed numbers of adjacent dots, the distance between dot defects should be more than 3mm apart.

11.3.2.1.3 The definitions of the inner display area and outer display area.

11.4 Inspection standards table:

11.4.1 Major defect

Item No.	Items to be	Inspection Standard	Classification of defects	
11.4.1.1	All functional defects	 No display Display abnormally Missing vertical/horizontal segment Short circuit Back-light no lighting, flickering and abnormal lighting. 	Major	
11.4.1.2	Missing	Missing component		
11.4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.		
11.4.1.4	linearity	No more than 1.5%		



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11.4.2 Cosmetic Defect (spot defect)

Item No	Itemsto be	Inspect	ion Standard		Classification of defects			
	Clear Spot Black and white		k/white spot, size x +y)/2	F is defin	ned x) ↓ ^y	Minor	
11.4.2.1	Spot defect Pinhole,		Zone	A	Acceptable B	Qty C	-	
	Foreign Particle, polarizer Dirt		F=0.15 F=0.20	Igno 2 1 0	pre	Ignore	Minor	
			Zone	1	Acceptable	Qty		
			ze(mm)	А	В	С		
11.4.2.2	Clear Spot TP Dirt	0.10<	F =0.15 F =0.25	Igno 2 1	ore	Ignore	Minor	
		F> 0.		0				
	Dim Spots		Zone	_	Acceptable	Otv		
	Circle	Siz	Size(mm)		B	C C	-	
	shaped and	F=0.2		A Igno			-	
11.4.2.3	dim edged	0.20<	F=0.4	2		_	Minor	
	defects	0.4<	F=0.6	1		Ignore		
		F > 0.	F > 0.6		0			
		dot =su	ıb-pixel					
			•	Acceptable Qty		Qty		
	_			Ι		II		
11.4.2.4	Dot defect	Br	ight dot	0		2	- Minor	
		D	ark dot	1		2		
			The distance of two point >5mm					
11.4.3 Co	smetic Defect	(linear defect	t)					
Item No	Items to be		Inspection Standard				Classification of defects	
			Size(mm) Acceptable Qty		le Oty			
	Line defect				zone	- •		
	Black line,	L(Length)	W(Width)	A B		C	-	
11.4.3.1	White line, Foreign	Ignore	W=0.02		Ignore		Minor	
	material on	L=3.0	0.02< W=0.03		2	т		
	polarizer	L=2.0	0.03< W=0.05		1	Ignore		
			W> 0.05	Define	efine as spot defect			



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11.4.3.2	Foreign Material on TP film	The line can be seen after mobile phone in the operating condition:								
		Size(mm)			Acceptable Qty					
		L(Length) W(Width)		zone						
					A	_	В	С	Minor	
		Ignore	W=0.0			Ignore				
		L=3.0	0.03 < W=0.05		3		Ignore			
			W> 0.05 Define as spot defect							
11.4.3.3	Dim line defect Polarizer &BL scratch TP film scratch	If the scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 11.4.3.1. If the scratch can be seen only in non-operating condition or some special angle, judge by the following.								
		Size(mm)			Acceptable Qty					
				zone						
		L(Length)	L(Length) W(Width)		A			С	Minor	
		Ignore	W=0.02		Ignore					
		L=3.0	0.02<	W=0.03		2 Ignore		_		
		L=2.0	0.03<	W=0.05				Ignore		
		2 210	W> 0		Define	e as spot	t defect			
	Polarize Air bubble	Air bubbles between glass & polarizer Acceptable Qty								
11.4.3.4				•		-		C		
				A		В		C		
		F=0.2 Ignore					Minor			
		0.20< F=0.3		2		Ignore				
		0.3< F=0.5			1			1811010		
		F > 0.5			0					
11.4 4 Ch	ipping Defect						I			
			-	. ~					Classification	
Item No	Items to be	Inspection Standard of defects								
	Glass defect	Chips on corner							Minor	
		A:LCD Glass defect								
11.4.4.1										
		=0.2 =S Disregard								
		Notes: S=contact pad length Chips on the corner of terminal shall not be allowed to extend into the								
		ITO pad or expose perimeter seal.								
		B:TP Glass defect								
		X Y T								
		$\begin{array}{c c c c c c c c c c c c c c c c c c c $								

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		Usual surface cracks A:LCD Glass defect X Y Z =3.0 <inner border="" disregard<br="" line="" of="" seal="" the="">B:TP Glass defect X Y Z =6.0 $=2.0$ Disregard Crack: Cracks tend to break are not allowed.</inner>		
11.4.5 Par	rts Defect		Classification	
Item No	Items to be	Inspection Standard	of defects	
11.4.5.1	Parts contra position	 Not allow IC and FPC/heat-seal lead width is more than 50% beyond lead pattern. Not allow chip or solder component is off center more than 50% of the pad outline. 	Major	
11.4.5.2	SMT	According to the <acceptability electronic<br="" of="">assemblies>IPC-A-610C class 2 standard. Component missing or function defect are Major defect, the others are Minor defect.</acceptability>	Major	
11.4.5.3	TP Defect	 1、 Pattern font : Pattern fonts are clear and symmetrical , pattern fonts filter lightly are allowed; The fort line is not allow to thinner or thicker than 1/3 of normal size, and swing is not more than 0.1mm. the line is smooth and not broken. Pattern font 2、 The wing forward in the side of Visual Area : The length of wing forward inside of the Visual Area: n=0.2mm ; Not excess 3 point , and the distance D=20mm_o 	Major	

